



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: SR0003-02 DATE: 5/3/00
 Product Affected: 71V016S, 71V124S, 71V016SA, 71V124SA
 Manufacturing Location Affected: N/A
 Date Effective: 8/3/00

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark "H" character on top mark
 Back Mark
 Date Code
 Other

Contact: Mary Vesey
 Title: Director of Quality
 Phone #: (831)-754-4565
 Fax #: (831)-754-4672
 E-mail: Mary.vesey@idt.com

Attachment: Yes No
 Samples: Available on request

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process Die Shrink : From "K" Die revision to "H".
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY:

Qualification is expected to be completed 6/15/00 and will be available upon request.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*
 Name/Date: _____ E-Mail Address: _____
 Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PCN Summary

PCN Type: Mask/Design Change for Die Shrink

Commodity: Memory

Forecast or Execute: Execute

Planned or Unplanned: Planned

Data Sheet Change: No

Detail of Change

Die Revision K Step H Step

Wafer Fab Facility	Hillsboro, OR	Hillsboro, OR
Wafer Fab Technology	Cmos 11.5	Cmos 11.5
Wafer Size	8 inch	8 inch
Cell Type	6T	6T
# Poly Layers	1	1
# Metal Layers	3	3
Die Dimension (sq mils)	28.3k	15.3k

Conversion schedule (Estimated)

	Sample Availability	Production Shipments
71V016S	6/1/00	7/24/00
71V124S	6/1/00	7/24/00
71V016SA	6/15/00	7/24/00
71V124SA	6/15/00	7/24/00



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Qualification Plan QS 9811-12

Test Vehicle: 71V016S

Expected Completion Date:

6/15/00 7/15/00

	Lot SS / Acc #	Lot # 1	Lot # 2
Dynamic Life Test: 750 hours @ +135°C, 4Vcc	116 / 0		
High Temp Storage Test: 1000 hours @ +150°C	77 / 0		
Temperature Cycle: -65°C to +150°C, 1000	45 / 0		
HAST: 100 hours @ +130°C/85% R.H. 100	45 / 0		
Autoclave: Unbiased 2 ATM Saturated Steam @	45 / 0		
ESD: Human Body Model	12 / 0		
ESD: Charged Device Model	12 / 0		
Latch-Up Immunity	6 / 0		
Bake & Ballshear Test: +200°C - 48 hour	20 / 0		

Characterization Data: Characterization will be completed as part of product qualification and data available upon request.